

AMENDMENT TRANSMITTAL LETTER (Large Entity)					Docket No. 24317/81501
Applicant(s): Shibaek Nam, et al.					
Serial No. 10/038,714	Filing Date: 01/02/2002	AUG 21 2003 U.S. PATENT & TRADEMARK OFFICE	Examiner Pershelle L. Greene	Group Art Unit 2826	
Invention: Semiconductor Device Having Multi-Chip Package Structure					
<u>TO THE ASSISTANT COMMISSIONER FOR PATENTS:</u>					
Transmitted herewith is an amendment in the above-identified application.					
The fee has been calculated and is transmitted as shown below.					
CLAIMS AS AMENDED					
	CLAIMS REMAINING AFTER AMENDMENT	HIGHEST # PREV. PAID FOR	NUMBER EXTRA CLAIMS PRESENT	RATE	ADDITIONAL FEE
TOTAL CLAIMS	14 -	49 =	0	x \$18.00	\$0.00
INDEP. CLAIMS	2 -	3 =	0	x \$84.00	\$0.00
Multiple Dependent Claims (check if applicable) <input type="checkbox"/>					\$0.00
TOTAL ADDITIONAL FEE FOR THIS AMENDMENT					\$0.00
<p><input type="checkbox"/> No additional fee is required for amendment.</p> <p><input type="checkbox"/> Please charge Deposit Account No. _____ in the amount of _____ A duplicate copy of this sheet is enclosed.</p> <p><input type="checkbox"/> A check in the amount of _____ to cover the filing fee is enclosed.</p> <p><input checked="" type="checkbox"/> The Commissioner is hereby authorized to charge payment of the following fees associated with this communication or credit any overpayment to Deposit Account No. 50-1597 A duplicate copy of this sheet is enclosed.</p> <p><input checked="" type="checkbox"/> Any additional filing fees required under 37 C.F.R. 1.16.</p> <p><input checked="" type="checkbox"/> Any patent application processing fees under 37 CFR 1.17.</p>					
 <i>Philip W. Woo</i> Signature					
Dated: August 21, 2003					
Philip W. Woo Attorney of Record Reg. No. 39,880					
<div style="border: 1px solid black; padding: 5px;"> I certify that this document and fee is being deposited on _____ with the U.S. Postal Service as first class mail under 37 C.F.R. 1.8 and is addressed to the Assistant Commissioner for Patents, Washington, D.C. 20251. </div>					
<div style="border: 1px solid black; padding: 5px;"> Signature of Person Mailing Correspondence </div>					
<div style="border: 1px solid black; padding: 5px;"> Express Mail Label No.: EV 305 257 695 US </div>					
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P11LARGE/REV06					



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

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In re application of: Shibaek Nam, et al.
Title: Semiconductor Device Having Multi-Chip Package
Structure
Application No.: 10/038,714
Filing Date: January 2, 2002
Examiner: Pershelle L. Greene
Group Art Unit: 2826
Confirmation No.: 8922
Law Office: Sidley Austin Brown & Wood LLP
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Dear Sir:

This is a Response to the Office Action dated May 21, 2003 for the above-referenced Application. Applicants respectfully requests reconsideration of the Application in view of the following amendments and remarks.